



Material Content Data Sheet



Sales Product Name		SAK-XE169FH-200F100L AB		Issued		19. July 2018		
MA#		MA001048998						
Package		PG-LQFP-176-12		Weight*		2017.17 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	71.686	3.55	3.55	35538	35538
leadframe	inorganic material	phosphorus	7723-14-0	0.149	0.01		74	
	non noble metal	zinc	7440-66-6	0.594	0.03		295	
	non noble metal	iron	7439-89-6	11.887	0.59		5893	
wire	non noble metal	copper	7440-50-8	482.643	23.93	24.56	239268	245530
	noble metal	gold	7440-57-5	4.995	0.25	0.25	2476	2476
	encapsulation	organic material	carbon black	1333-86-4	7.063	0.35		3502
encapsulation	plastics	epoxy resin	-	190.712	9.45		94544	
	inorganic material	silicondioxide	60676-86-0	1214.905	60.22	70.02	602282	700328
leadfinish	non noble metal	tin	7440-31-5	15.144	0.75	0.75	7507	7507
plating	noble metal	silver	7440-22-4	2.988	0.15	0.15	1482	1482
glue	plastics	epoxy resin	-	3.600	0.18		1785	
	noble metal	silver	7440-22-4	10.800	0.54	0.72	5354	7139
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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